


LTR	MIN	MAX
A IN.	—	.104
MM	—	2.64
A1 IN.	.004	—
MM	.102	—
A2 IN.	.082	.094
MM	2.08	2.39
b IN.	.014	.020
MM	0.36	0.51
C IN.	.006	.013
MM	0.15	0.33
D IN.	.810	.824
MM	20.57	20.93
e IN.	.050 BSC	
MM	1.27 BSC	
E1 IN.	.292	.299
MM	7.42	7.59
H IN.	.405	.419
MM	10.29	10.64
L IN.	.021	.041
MM	0.53	1.04
G IN.	.014 BSC	
MM	0.36 BSC	

NOTES:

- 1 A TERMINAL 1 IDENTIFIER MUST BE POSITIONED SO THAT 1/2 OR MORE OF IT'S AREA IS CONTAINED IN THE HATCHED ZONE.
- 2 "D" AND "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .003 INCHES PER SIDE.
- 3 DIMENSION "b" IS MEASURED BELOW THE LOWER RADIUS OF THE FOOT.

SIGNATURE		DATE		 Dallas Semiconductor			
DOC. CONTROL:							
ENGR. MGP:							
MFG. ENGR:							
CHECKED BY:							
DRAWN BY:				TITLE MARKETING OUTLINE— .300" SOIC 32 LEAD .050" PITCH			
		SIZE A	FSCM NO	PART NO.		REV A	
DO NOT SCALE DWG.		SCALE N/A				SHEET 1 OF 1	